					 					F	REVI	SIOI	VS												
LTR					 		DE	SCRI	PTIC	W								D	TE (/R-M	D-DA)	Π	APPI	ROVI	:D
REV																									П
SHEET	_						<u> </u>																		П
REV	4	_			 			L	L	L.	L														
SHEET	\perp L	┵				L_		L.,	_																
REV STATE		L	RE	V	 _				L.		L														
PMIC N/A	-	1_	SH	EET	_	2 PARE			5	6	7	8	9 10 11 12 13												
STAND MIL DRA THIS DRAW FOR USE BY AND AG	ITA AWI ING IS ALL E	RY NC S AV S EPA	AILA ARTM F THI	BLE ENT	DRA	PROVE LLL WING	ED BY	DEFENSE ELE DAY MICROCIRCUIT, DI LOW POWER SCHOTT																	
AMSC N/		F DI	FEN	SE	REV	SION	LEV	EL.					l	···	HEE		1)F			13	_	1

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5962-E1511

1. SCOPE			
1.1 Scope. This drawing descript 1.2.1 of MIL-STD-883, "Pronon-JAN devices".	cribes device revisions for the	quirements for cl use of MIL-STD-88	ass B microcircuits in accordance
1.2 Part number. The complete	te part number s	hall be as shown	in the following example:
<u>5962-89956</u>	01	K 	X T !
Drawing number	Device type (1.2.1)	Case outline (1.2.2)	l Lead finish per MIL-M-38510
1.2.1 Device type. The device	e type shall ide		
Device type Generic num	nber	Circuit f	unction
01 54AL S646	0000.	bus transceivers inverting 3-stat	and registers with e outputs
1.2.2 <u>Case outlines</u> . The cas and as follows:	e outlines shall	be as designate	d in appendix C of MIL-M-38510,
Outline letter		Case outl	ine
K F-6 L D-9 3 C-4	(24-lead, .640" (24-lead, 1.280 (28-terminal, .	x .420" x .090" " x .310" x .200 460" x .460" x .3), flat package "), dual-in-line package 100"), square chip carrier package
1.3 Absolute maximum ratings.			
Supply voltage range V _{CC} - DC input voltage:			-0.5 V dc to +7.0 V dc
Control inputs I/O ports Storage temperature range Maximum power dissipation (-1.2 V dc at -18 mA to +7.0 V dc -1.2 V dc at -18 mA to +5.5 V dc -65°C to +150°C 484 mW
Lead temperature (soldering Thermal resistance, junction Junction temperature (T _J)	n-to-case (ค.เก) -		+300°C See MIL-M-38510, appendix C +175°C
1/ Maximum power dissipation i due to short circuit test,	s defined as V _{CC} e.g., I _O .	$_{ m C}$ x I $_{ m CC}$, and must	withstand the added PD

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1.4 Recommended operating conditions.				
Supply voltage range (V _{CC})			+4.5 V maximum	
Minimum high level input voltage (V _I Maximum low level input voltage (V _{IL} T _C = +125°C			2.0 V d	c c
Maximum high level output current (I	ω) ·		12 mA	
Maximum low level output current (I _C Case operating temperature range (T _C Pulse duration, clocks high or low (Setup time, A before CAB+ or B befor Hold time, A after CAB+ or B after C) ;) t _W) e CBA+ (t	 	12 mA 55°C t 14.5 ns 15.0 ns	o +125°C minimum minimum minimum
2. APPLICABLE DOCUMENTS				
2.1 Government specification, standard following specification, standard, and bu Department of Defense Index of Specificat part of this drawing to the extent specif	lletin of ions and S	the i Standa	i hatzil auzz	n that iccup of the
SPECIFICATION				
MILITARY				
MIL-M-38510 - Microcircuit	s, General	Spec	ification for	
STANDARD				
MILITARY				
MIL-STD-883 - Test Methods	and Proce	dures	for Microelec	ctronics.
BULLETIN				
MILITARY				
MIL-BUL-103 - List of Stand	dardized M	lilitan	ry Drawings (S	SMD's).
(Copies of the specification, standard, with specific acquisition functions should directed by the contracting activity.)	and bulle d be obtai	tin re ned fr	equired by mar rom the contra	nufacturers in connection acting activity or as
2.2 Order of precedence. In the event references cited herein, the text of this	of a conf drawing s	lict b hall t	etween the teake precedenc	ext of this drawing and the
3. REQUIREMENTS				
3.1 Item requirements. The individual MIL-STD-883, "Provisions for the use of MI devices" and as specified herein.	item requ L-STD-883	iremen in co	ts shall be i njunction wit	n accordance with 1.2.1 of h compliant non-JAN
3.2 <u>Design, construction, and physical</u> dimensions shall be as specified in MIL-M-	dimension 38510 and	s. Th Therei	e design, con n.	struction, and physical
			T	·
STANDARDIZED	SIZE			
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- 3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.
- 3.2.2 Truth table. The truth table shall be as specified on figure 2.
- 3.2.3 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.
- 3.2.4 Test circuit and switching waveforms. The test circuit and switching waveforms shall be as specified on figure 3.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and apply over the full case operating temperature range.
- 3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.
- 3.5 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in MIL-BUL-103 (see 6.6 herein).
- 3.6 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.6 herein). The certificate of compliance submitted to DESC-ECC prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 Notification of change. Notification of change to DESC-ECC shall be required in accordance with MIL-STD-883 (see 3.1 herein).
- 3.9 <u>Verification and review.</u> DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
 - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).
- 4.2 <u>Screening.</u> Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.6 herein).
 - (2) $T_A = +125^{\circ}C$, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

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Test	Symbol	 	Conditions $-55^{\circ}\text{C} \leq \text{T}_{\text{C}} \leq +125^{\circ}\text{C}$ unless otherwise specified $\underline{1}/$			ĺ	its Max	i Unit
High level output voltage	VOH	Y _{CC} = 4.5 V Y _{IH} = 2.0 V	V _{IL} = 0.8 V	I _{OH} = -0.4 mA	1,3	2.5		V
	į I	i i	V _{IL} = 0.7 V		2	2.5	į	į
	 	i <u>2</u> / I	V _{IL} = 0.8 V	11 _{OH} = -3.0 mA	1,3	2.4	 	i i
		 	 V _{IL} = 0.7 V		2	2.4		i I I
] [V _{IL} = 0.8 V	I _{OH} = -12 mA	1,3	2.0	 	Ì
	 	[] }	V _{IL} = 0.7 V		2	2.0		
ow level	~~	 Y _{CC} = 4.5 V Y _{IH} = 2.0 V	V _{IL} = 0.8 V		1,3		0.4	V
voltage		$\begin{bmatrix} I_{OL} = 12 \text{ mA} \\ \frac{2}{I} \end{bmatrix}$	V _{IL} = 0.7 V] 3 		0.4	
Input clamp voltage	v _{IC}	$V_{CC} = 4.5 V$	$I_{IN} = -18 \text{ mA}$		1,2,3		-1.2	V
figh level	I _{IH1}	 V _{CC} = 5.5 V	V _{IN} = 7.0 V	Control inputs	1,2,3		0.1	mA
current			V _{IN} = 5.5 V	A or B ports			0.1	
	I _{IH2}	<u>3</u> /	V _{IN} = 2.7 V	Control inputs			20	μА
			<u> </u>	I I A or B ports			20	<u> </u>
ow level input current	IIL	$V_{CC} = 5.5 \text{ V}, \frac{3}{4}$	$V_{IN} = 0.4 V$	Control inputs	1,2,3		-0.2	 mA
utput current	I ₀	V _{CC} = 5.5 V,	V _{OUT} = 2.25 V	A or B ports	1,2,3	1	-0.2 -112	mA

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			Condit -55°C <u><</u> T _C		Group A	! Lim 	 Unit	
		l unla	ess otherwise	specified 1/		Min	Max	-[
Supply current	^I ССН	V _{CC} = 5.5 V		Outputs high	1,2,3		76	l mA
	ICCL			Outputs low		' 	 88	j
	Iccz			Outputs disabled	 		 88 	i l l
Functional tests	1	See 4.3.1c	<u>5</u> /		7,8	i	 	T
Maximum frequency	 f _{MAX} 	V _{CC} = 4.5 V t C _L = 50 pF	to 5.5 V		9,10,11	35		MHz
Propagation delay time,	t _{PLH1}	$\begin{array}{l} R_1 = 500\Omega \\ R_2 = 500\Omega \\ \end{array}$			9,10,11	10	35	ns
CBA, CAB to An, Bn	t _{PHL1}	 - -	<u>6</u> /			5	20	
Propagation delay time,	 t _{PLH2} 			;	9,10,11	5 i	22	ns
An, Bn to Bn, An	 t _{PHL2} 	- 				3	15	
delay time,	t _{PLH3}	1			9,10,11	10	40	ns
SBA, SAB to An, Bn (with An, Bn low)	t _{PHL3}] 				5	23	: :
Propagation delay time,	t _{PLH4}	î 			9,10,11	8	30	ns
SBA, SAB to An, Bn (with An, Bn high) 7/	^t PHL4	 				5	24	
nable time, G to An, Bn	^t PZH1	 		•	9,10,11	3	20	ns
 	፟፟፟tPZL1]	5	22	
See footnotes at	end of ta	able.			·	<u>-</u>	<u>.</u>	
STAND MILITARY	ARDIZE		SIZE A		F0.50	-89956		

Test	[Symbol	Conditions $\begin{array}{ccc} & & & & & & \\ & & & & -55^{\circ}C & \leq & T_{C} & \leq & +125^{\circ}C \end{array}$	Group A subgroups	Lim	 Unit	
		unless otherwise specified 1/			Max	1
Disable time, G to An, Bn	t _{PHZ1}	V _{CC} = 4.5 V to 5.5 V C _L = 50 pF	9,10,11	1	1 12	ns
	t _{PLZ1}	R ₁ = 500Ω R ₂ = 500Ω See figure 6		1	20	
Enable time, DIR to An, Bn	t _{PZH2}	<u>6/</u> -	9,10,11	5	 38	l ns
	t _{PZL2}			5	30	
Disable time, DIR to An, Bn	t _{PHZ2}		9,10,11	1	12	ns
	t _{PLZ2}	<u> </u>	!	2	21	!

- Unused inputs that do not directly control the pin under test must be put at \geq 2.5 V or \leq 0.4 V. No unused inputs shall exceed 5.5 V or go less than 0.0 V. No inputs shall be floated.
- 2/ All outputs must be tested. In the case where only one input at VIL maximum or VIH minimum produces the proper state, the test must be performed with each input being selected as the VIL maximum or VIH minimum input.

For I/O ports, the parameters I_{IH2} and I_{II} include the off-state output current. The output conditions have been chosen to produce a current that closely approximates one half of the true short circuit output current, I_{OS} . Not more than one output will be tested at one time and duration of the test condition shall not exceed one second. Functional tests shall be conducted at input test conditions of GND \leq $V_{IL} \leq$ V_{OL} and

 $V_{OH} \leq V_{IH} \leq V_{CC}$. 6/ Propagation delay limits are based on single output switching. Unused inputs = 3.5 V or < 0.3 V.

These parameters are measured with the internal output state of the storage register opposite to that of the bus input.

- 4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-SID-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
 - 4,3.1 Group A inspection.
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 4, 5, and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
 - c. Subgroups 7 and 8 shall verify the truth table as specified on figure 2.

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0 K and L Terminal	1 3
	3
Terminal	
	symbol
CAB SAB DIR A1 A2 A3 A4 A5 A6 A7 A8 GND B8 B7 B6 B5 B4 B3 B2 B1 G SBA CBA CBA	NC CAB SAB DIR A2 A3 NC A4 A5 A6 A7 A8 GND NC B87 B6 B5 B4 B3 NC B2 B1 G CBA CBA CCC
	SAB DIR A1 A2 A3 A4 A5 A6 A7 A8 GND B8 B7 B6 B5 B4 B3 B2 B1 GND

NC = No connection

FIGURE 1. Terminal connections.

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-	Inputs				Dat	a I/O	1		
G	DIR	CAB	СВА	SAB	SBA	A1 THRU A8	B1 THRU B8	Operation mode	
X X H H L L	H X X	† X † H/L X X X H/L	X + + +/L X H/L X	X X X X X L H	X X X L H X	Input Unspecified 1/ Input Input Output Output Input Input Input Input Input	Unspecified 1/ Input Input Input Input Input Input Output Output	Store A, B unspecified 1/ Store B, A unspecified 1/ Store A and B data Isolation, hold storage Real-time B data to A bus Stored B data to A bus Real-time A data to B bus Stored A data to B bus	

H = High logic level L = Low logic level

↑ = Transition from a low to a high logic level

X = Irrelevant

H/L = High or low logic level

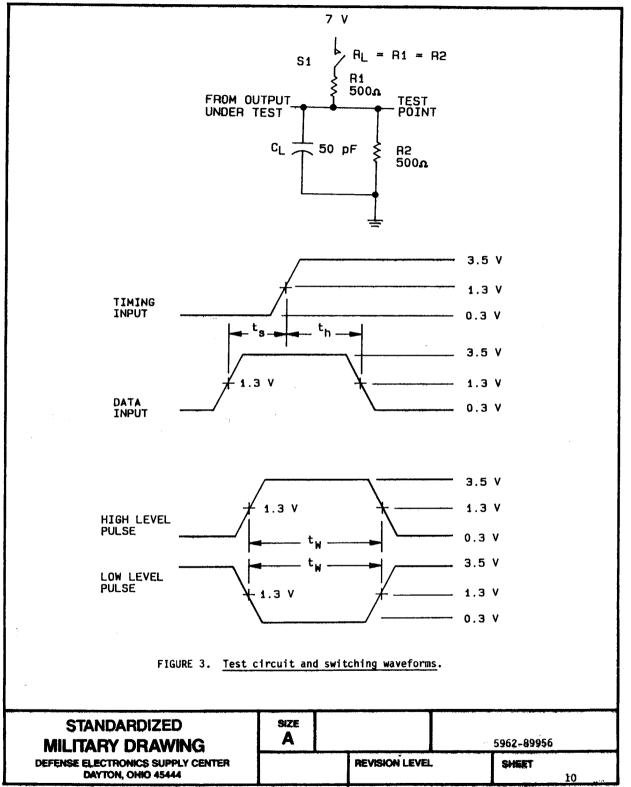
1/ The data output functions may be enabled or disabled by various signals at the \overline{G} and DIR inputs. Data input functions are always enabled, i.e., data at the bus pins will be stored on every low to high transition on the clock inputs.

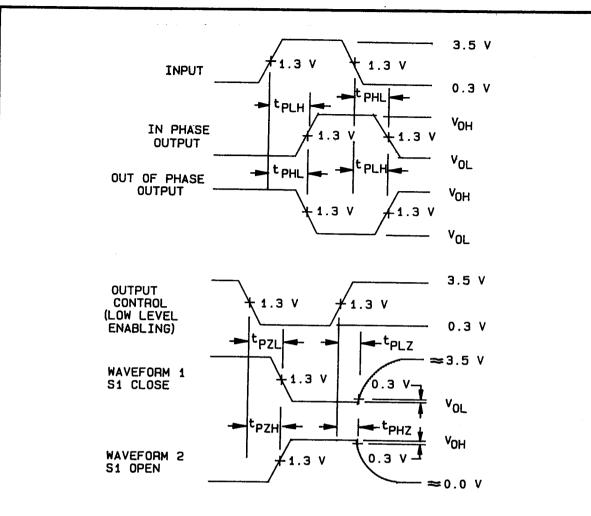
FIGURE 2. Truth table

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NOTES:

C_L includes probe and jig capacitance.

- 1. 2. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
- Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- When measuring propagation delay items of three-state outputs, switch S1 is open. The outputs are measured one at a time with one input transition per measurement. All input pulses have the following characteristics: $PRR \le 10 \text{ MHz}$, duty cycle = 50 percent, $t_r = t_f = 3 \text{ ns } \pm 1 \text{ ns.}$

FIGURE 3. Test circuit and switching waveforms - Continued.

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TABLE II. Electrical test requirements.

 MIL-STD-883 test requirements 	Subgroups (per method 5005, table I)		
 Interim electrical parameters (method 5004) 			
 Final electrical test parameters (method 5004)	*1, 2, 3, 7, 8, 9, 10, 11		
l Group A test requirements (method 5005)	1 1, 2, 3, 7, 8, 9, 10, 11		
 Group C and D end-point electrical parameters (method 5005)	1,2,3		

^{*}PDA applies to subgroup 1.

4.3,2 Groups C and D inspections.

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test conditions, method 1005 of MIL-STD-883.
 - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.6 herein).
 - (2) $T_A = +125^{\circ}C$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

6. NOTES

- 6.1 <u>Intended use.</u> Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
- 6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-481 using DD Form 1693, Engineering Change Proposal (Short Form).

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- 6.4 Record of users. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and the applicable SMD. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DESC-ECC, telephone (513) 296-6022.
- 6.5 Comments. Comments on this drawing should be directed to DESC-ECC, Dayton, Ohio 45444, or telephone (513) 296-8525.
- 6.6 Approved sources of supply. Approved sources of supply are listed in MIL-BUL-103. Additional sources will be added to MIL-BUL-103 as they become available. The vendors listed in MIL-BUL-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-ECC. The approved source of supply listed below is for information purposes only and is current only to the date of the last action of this document.

Military drawing part number	Vendor CAGE number	Vendor similar part number 1/
5962-8995601LX	01295	SNJ54ALS646JT
5962-8995601KX	01295	SNJ54ALS646W
5962-89956013X	01295	SNJ54ALS646FK

1/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number

Vendor name and address

01295

Texas Instruments, Incorporated P.O. Box 60448 Midland, TX 79711-0448

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